

Product Change Notification - LIAL-19RTVJ812

Date:

23 Apr 2018

Product Category:

Memory; Real-Time Clock/Calendar Affected CPNs:

Notification subject:

CCB 3230 Initial Notice Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 160K wafer technology available in 8L MSOP package at MTAI site.

Notification text:

PCN Status:

Initial notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 160K wafer technology available in 8L MSOP package at MTAI assembly site.

Pre Change:

Using gold (Au) bond wire

Post Change:

Using palladium coated copper with gold flash(CuPdAu) bond wire.

Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)				
Wire material	Au	CuPdAu				
Die attach material	8390A	8390A				
Molding compound material	G600V	G600V				
Lead frame material	C194	C194				

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:



June 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	April 2018					June 2018					
Workweek	14	15	16	17	18	>	22	23	24	25	26
Initial PCN Issue Date				Х							
Qual Report Availability							Х				
Final PCN Issue Date							Х				

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

April 23, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_LIAL-19RTVJ812_QUAL_PLAN.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

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To opt out of future offer or information emails (other than product change notification emails), click here to go to microchip DIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

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Affected Catalog Part Numbers (CPN)

11AA010-I/MS 11AA010T-I/MS 11AA020-I/MS 11AA020T-I/MS 11AA040-I/MS 11AA040T-I/MS 11AA080-I/MS 11AA080T-I/MS 11AA160-I/MS 11AA160T-I/MS 11AA161-I/MS 11AA161T-I/MS 11LC010-E/MS 11LC010-I/MS 11LC010T-E/MS 11LC010T-I/MS 11LC020-E/MS 11LC020-I/MS 11LC020T-E/MS 11LC020T-I/MS 11LC040-E/MS 11LC040-I/MS 11LC040T-E/MS 11LC040T-I/MS 11LC080-E/MS 11LC080-I/MS 11LC080T-E/MS 11LC080T-I/MS 11LC160-E/MS 11LC160-I/MS 11LC160T-E/MS 11LC160T-I/MS 11LC161-E/MS 11LC161-I/MS 11LC161T-E/MS 11LC161T-I/MS 24AA014H-I/MS 24AA014HT-I/MS 24AA014-I/MS 24AA014T-I/MS 24AA01H-I/MS 24AA01HT-I/MS 24AA01-I/MS 24AA01T-I/MS 24AA024H-I/MS 24AA024HT-I/MS 24AA024-I/MS

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24AA025-I/MS 24AA025T-I/MS 24AA02H-I/MS 24AA02HT-I/MS 24AA02-I/MS 24AA02-I/MSB31 24AA02T-I/MS 24AA02T-I/MSB31 24AA52-I/MS 24AA52T-I/MS 24C01C-E/MS 24C01C-I/MS 24C01CT-E/MS 24C01CT-I/MS 24C02C-E/MS 24C02C-I/MS 24C02CT-E/MS 24C02CT-I/MS 24LC014-E/MS 24LC014H-E/MS 24LC014H-I/MS 24LC014HT-E/MS 24LC014HT-I/MS 24LC014-I/MS 24LC014T-E/MS 24LC014T-I/MS 24LC01B-E/MS 24LC01BH-E/MS 24LC01BH-I/MS 24LC01BHT-E/MS 24LC01BHT-I/MS 24LC01B-I/MS 24LC01BT-E/MS 24LC01BT-I/MS 24LC024-E/MS 24LC024H-E/MS 24LC024H-I/MS 24LC024HT-E/MS 24LC024HT-I/MS 24LC024-I/MS 24LC024T-E/MS 24LC024T-I/MS 24LC025-E/MS 24LC025-I/MS 24LC025T-E/MS 24LC025T-I/MS 24LC02B-E/MS 24LC02BH-E/MS 24LC02BH-I/MS

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24LC02BHT-I/MS 24LC02B-I/MS 24LC02BT-E/MS 24LC02BT-I/MS 24LCS52-I/MS 24LCS52T-I/MS 24VL014/MS 24VL014H/MS 24VL014HT/MS 24VL014T/MS 24VL024/MS 24VL024H/MS 24VL024HT/MS 24VL024T/MS 24VL025/MS 24VL025T/MS 34AA02-E/MS 34AA02-I/MS 34AA02T-E/MS 34AA02T-I/MS 34LC02-E/MS 34LC02-I/MS 34LC02T-E/MS 34LC02T-I/MS 34VL02/MS 34VL02T/MS MCP79400-I/MS MCP79400T-I/MS MCP79401-I/MS MCP79401T-I/MS MCP79402-I/MS MCP79402T-I/MS MCP7940M-I/MS MCP7940MT-I/MS MCP7940N-E/MS MCP7940N-I/MS MCP7940NT-E/MS MCP7940NT-I/MS MCP79410-I/MS MCP79410T-I/MS MCP79411-I/MS MCP79411T-I/MS MCP79412-I/MS MCP79412T-I/MS